

PHK31NQ03LT-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)			
30	0.003 at V _{GS} = 10 V	25			
	0.004 at V_{GS} = 4.5 V	22			

FEATURES

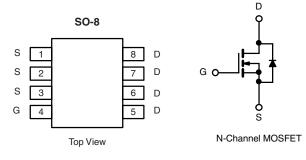
Halogen-free According to IEC 61249-2-21
Available



 Ultra Low On-Resistance Using High Density Trench Power MOSFET Technology

APPLICATIONS

- Synchronous Buck Low-Side
 - Notebook
 - Server
 - Workstation
- Synchronous Rectifier-POL



Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		V
Gate-Source Voltage		V _{GS}	± 20		v
	T _A = 25 °C	– I _D	25	17	
Continuous Drain Current $(T_J = 150 \text{ °C})^a$	T _A = 70 °C		20	13	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	70		Α
Continuous Source Current (Diode Conduction) ^a		۱ _S	2.9	1.3	
Avalanche Current		I _{AS}	50		
	T _A = 25 °C	– P _D	3.5	1.6	W
Maximum Power Dissipation ^a	T _A = 70 °C		2.2	1	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Mauinauna lugatian ta Anchianta	t ≤ 10 s	R _{thJA}	29	35		
Maximum Junction-to-Ambient ^a	Steady State	' 'thJA	67	80	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	13	16		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		3.0	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA		
Zero Gale voltage Drain Current		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$			5			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	30			А		
	Brach	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 25 \text{ A}$		0.003		Ω		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 22 \text{ A}$		0.004				
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 25 \text{ A}$		110		S		
Diode Forward Voltage ^a	V _{SD}	$I_{\rm S}$ = 2.9 A, $V_{\rm GS}$ = 0 V		0.72	1.1	V		
Dynamic ^b								
Input Capacitance	C _{iss}			6500				
Output Capacitance	C _{oss}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 20 A		930		pF		
Reverse Transfer Capacitance	C _{rss}			610				
Total Gate Charge	Qg			45	70			
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 20 A		20		nC		
Gate-Drain Charge	Q _{gd}			16		1		
Gate Resistance	R _g	f = 1.0 MHz		1.1		Ω		
Turn-On Delay Time	t _{d(on)}			27	40			
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		21	35	ns		
Turn-Off Delay Time	t _{d(off)}	$\rm I_D \cong 1$ A, $\rm V_{GEN}$ = 10 V, $\rm R_g$ = 6 Ω		107	160			
Fall Time	t _f			43	65			
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.9 A, dI/dt = 100 A/μs		45	70			

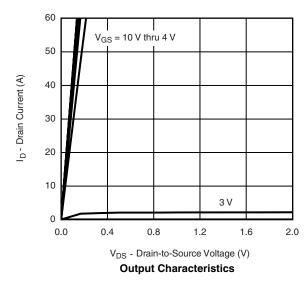
Notes:

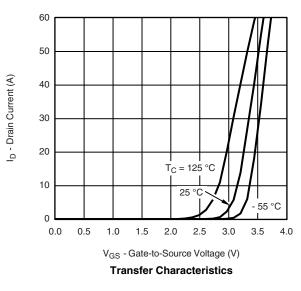
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

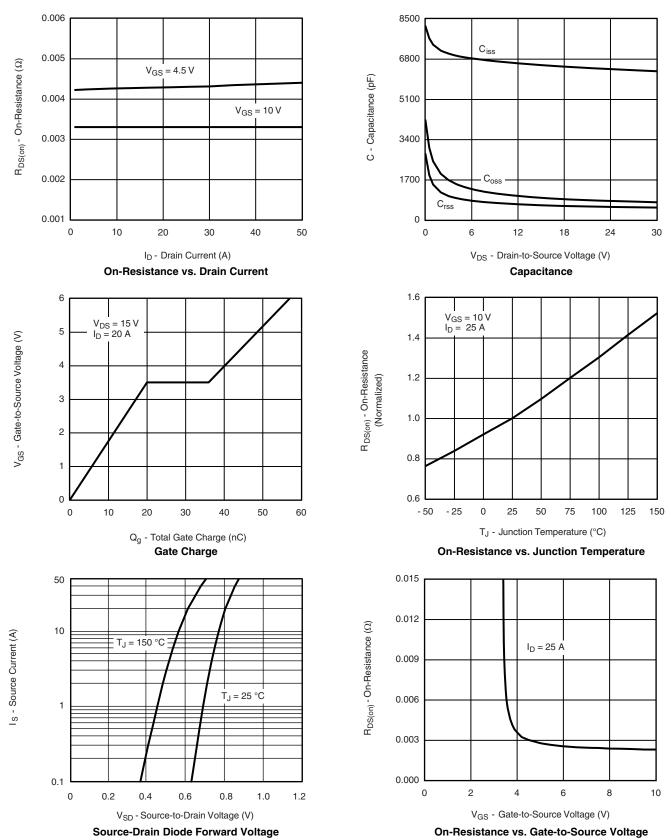




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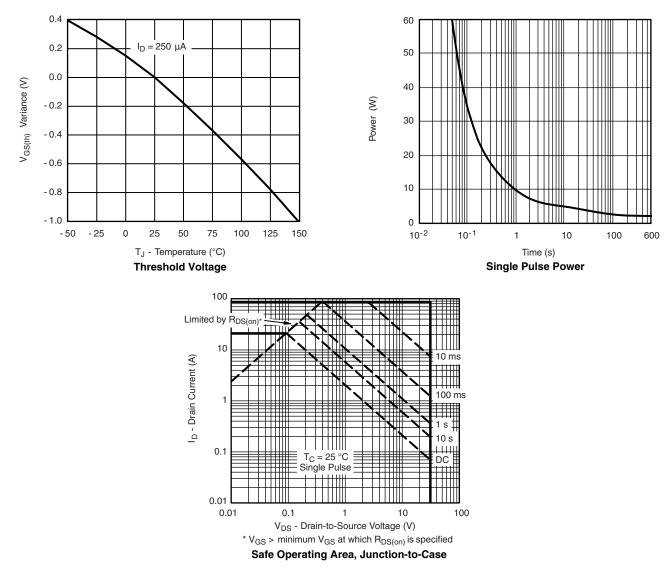


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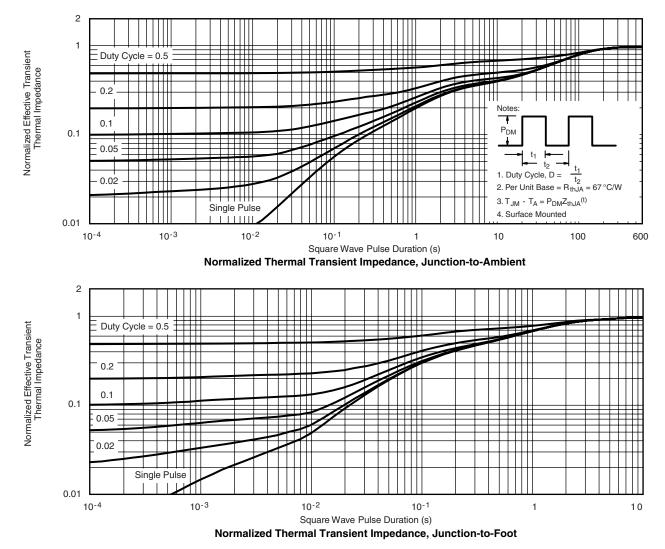




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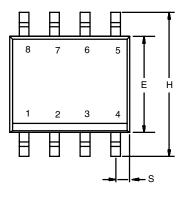


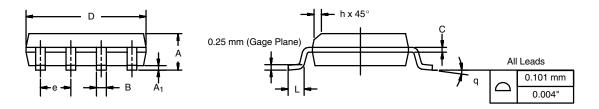


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

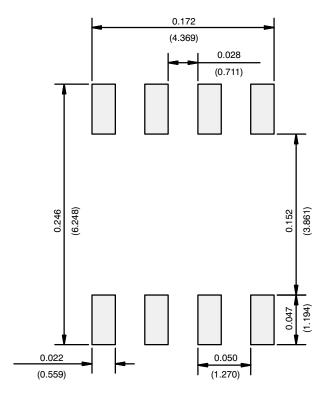




	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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